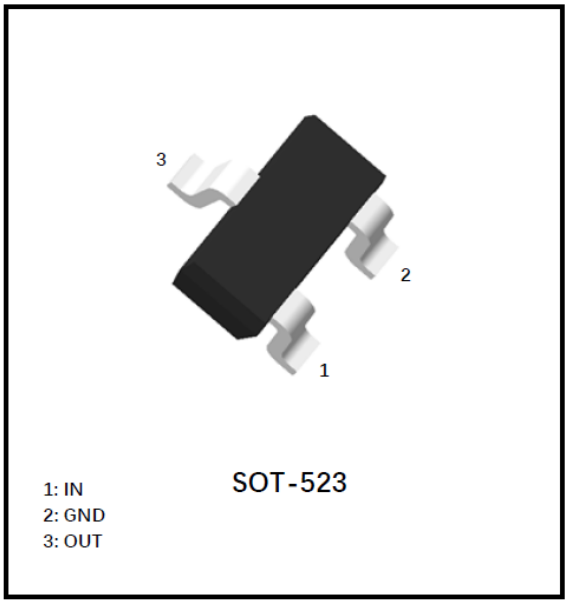
NPN Digital Transistors (Built-in Resistors)



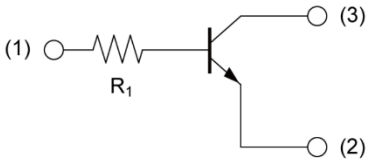
Features

- Moisture Sensitivity Level 1
- Surface mount package ideally Suited for Automatic Insertion
- Epoxy meets UL-94 V-0 flammability rating, halogen-free

Mechanical Data

- **Package**: SOT-523
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Marking:** 06

■Equivalent circuit



(1) BASE
(2) EMITTER
(3) COLLECTOR

■Maximum Ratings (Ta=25℃ Unless otherwise specified)

Item	Symbol	Unit	Conditions	Value
Collector-Emitter Voltage	V_{CEO}	V	I_C=1.0mA, I_B=0	50
Collector-Base Voltage	V_{CBO}	V	I_C=50uA, I_E=0	50
Emitter-Base Voltage	V_{EBO}	V	I_E=50uA, I_C=0	5
Collector Current	I_C	mA		100
Collector Power Dissipation	P_C	mW		150
Operation Junction Temperature	T_J	℃		-55 to +150
Storage Temperature	T_{STG}	℃		-55 to +150

■Electrical Characteristics (Ta=25℃ unless otherwise specified)

Item	Symbol	Unit	Conditions	Min	TYP	Max
Collector-Emitter Voltage	V_{CEO}	V	I_C=1.0mA, I_B=0	50		
Collector-Base Voltage	V_{CBO}	V	I_C=50uA, I_E=0	50		
Emitter-Base Voltage	V_{EBO}	V	I_E=50uA, I_C=0	5		
Collector-base Cut-off Current	I_{CBO}	uA	V_{CB}=50V			0.5
Emitter-base cut-off current	I_{EBO}	uA	V_{EB}=4V			0.5
DC Current Gain	h_{FE}		I_C=1mA, V_{CE}=5V	100		600
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	V	I_C=10mA, I_B=1mA			0.3
Input Resistance	R1	kΩ		32.9	47	61.1

■ Ordering Information (Example)

Preferred P/N	Packing Code	Unit Weight(G)	Minimum Package(Pcs)	Inner Box Quantity(Pcs)	Outer Carton Quantity(Pcs)	Delivery Mode
DTC144TE	F2	Approximate 0.0027	3000	30000	120000	7" reel

■ Characteristics (Typical)

Fig. 1 - Static Characteristics

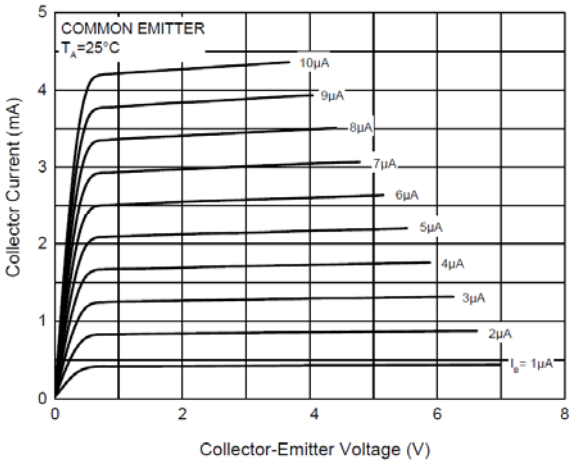


Fig. 2 - DC Current Gain Characteristics

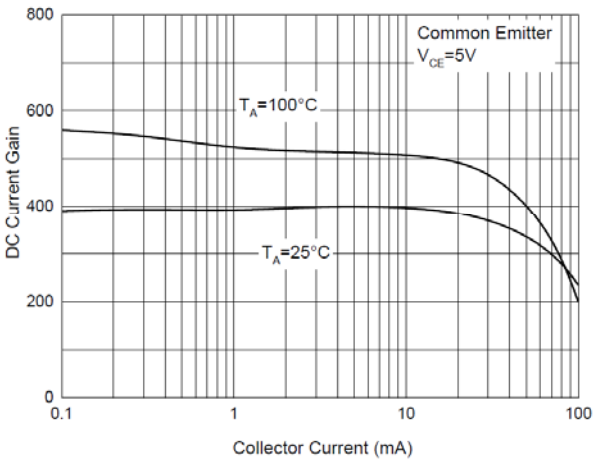


Fig. 3 - Collector-Emitter Saturation Voltage Characteristics

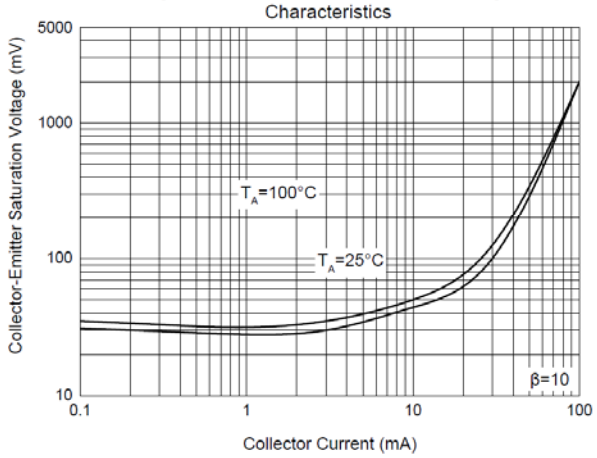
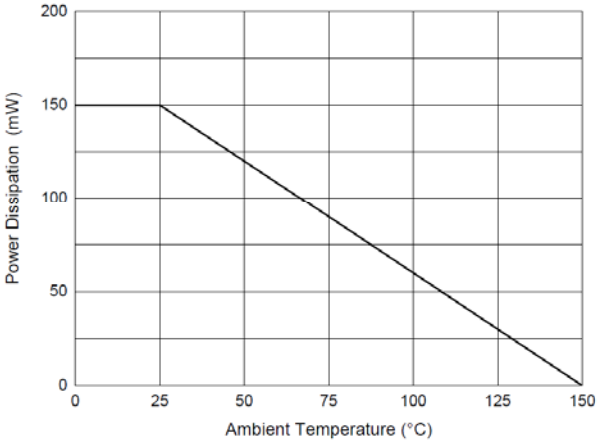
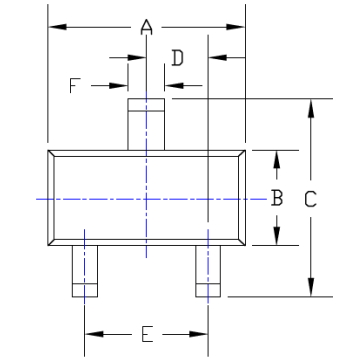


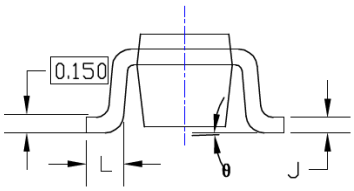
Fig. 3 - Power Derating Curve



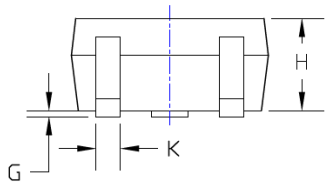
■ SOT-523 Package Outline Dimensions



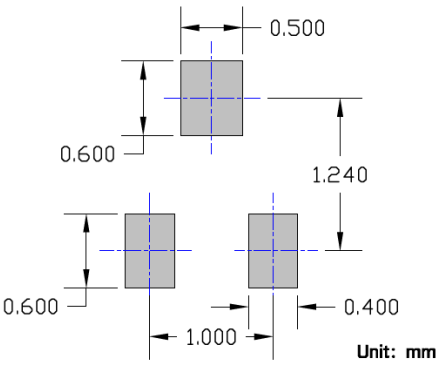
TOP VIEW



SIDE VIEW



SIDE VIEW



Unit: mm

Suggested Solder Pad Layout

SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.059	0.067	1.500	1.700
B	0.030	0.033	0.750	0.850
C	0.057	0.069	1.450	1.750
D	0.020TYP		0.500TYP	
E	0.035	0.043	0.900	1.100
F	0.010	0.018	0.250	0.450
G	0.000	0.004	0.000	0.100
H	0.024	0.031	0.600	0.800
J	0.004	0.008	0.100	0.200
K	0.006	0.014	0.150	0.350
L	0.010	0.018	0.260	0.460
θ	0°	8°	0°	8°

NOTE:
1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

Note:
1. All dimensions are in millimeters (mm) unless otherwise specified.
[所有尺寸均以毫米为单位，除非另有说明]
2. General tolerances: ±0.10mm unless otherwise specified.
[通用公差为±0.10mm，除非另有说明]
3. Dimensions and tolerances per ASME Y14.5M–2018.
[尺寸和公差遵循 ASME Y14.5M–2018 标准]
4.All dimensions shown are exclusive of burrs and gate residues. Burrs and gate vestiges shall not exceed 0.15 mm in maximum.
[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]
5.Dimension b does not include dambar protrusion of max 0.100 mm per side.
[尺寸b不包括单边最大0.100 MM的中筋凸出部分]
6.Dimensions A and B are the overall extreme outer dimensions of the mold compound. These dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.
[A和B是塑封体的外部极限尺寸，不包括包封溢料、内引线溢料、凸出部分以及胶体毛刺，但是包含了包封错位的最大尺寸]
7.Formed leads shall be planar with respect to one another within a maximum of 0.076 mm relative to the seating plane.
[成型的管脚应为同一平面，共面性最大为0.1mm]
8. ★It is the key size.
[★ 标记为关键尺寸]

Notice

All products, product specifications and data are subject to change without notice to improve reliability, function or design or otherwise. Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in STARSEA's terms and conditions of sale for such products, STARSEA assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of STARSEA products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.